Initial Product Change Notice (PCN)

Subject: Introduce alternate assembly facility of the listed Renesas ODFN packaged products and Minor changed to the POD
Publication Date: 8/6/2020
Effective Date: 6/15/2021

Revision Description:
Initial Release

Description of Changes:

1. Alternate assembly facility of the listed Renesas ODFN packaged products
   - *Advanced Semiconductor Engineering, Chung Li, Taiwan R.O.C (ASECL)*
2. Minor change to the Package Outline Drawing (POD).

Affected Device List
ISL76671AROZ-T7
ISL76671AROZ-T7A
ISL76671AROZ-T7R5503
ISL76671AROZ-T7R5534
ISL76671AROZ-TKR5534
ISL76683AROZ-T7
ISL76683AROZ-T7A

Reason for Change:
This notice is an Initial Product Change Notification to inform you about an upcoming change of alternate assembly facility of the listed Renesas ODFN (Optical Dual Flat No Lead) packaged products. Along with the site change, there is a minor change to the POD (Package Outline Drawing) with additional four (4) non-functional exposed pad (tie bar). Please see Appendix B for details.

Renesas Electronics America (REA) will qualify ASECL as alternate assembly facility. ASECL is existing assembly supplier for Renesas. Adding assembly site will expand current capabilities and capacities to optimize Renesas's ability to meet customer's delivery requirements. ASECL facility is ISO9001:2015 and IATF 16949:2016 certified.

Impact on fit, form, function, quality & reliability:
The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function or interchangeability of the product. A summary of the qualification plan and results will be provided for reference. Please refer Appendix A. The remainder of the manufacturing operations (wafer fabrication, package level electrical test, etc) will continue to be processed to previously established manufacturing flow.

Product Identification:
Customers may expect to receive product from the current facilities or ASECL facilities until the existing inventory is depleted or earlier with customer's approval.

Qualification status: In progress
Sample availability: 12/1/2020
Device material declaration: Available upon request

Note : Sample is available 12/01/2020 onwards, and subject to availability. Customer may expect 1 – 2 months for sample replenishment.

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Renesas within 30 days of the publication date.

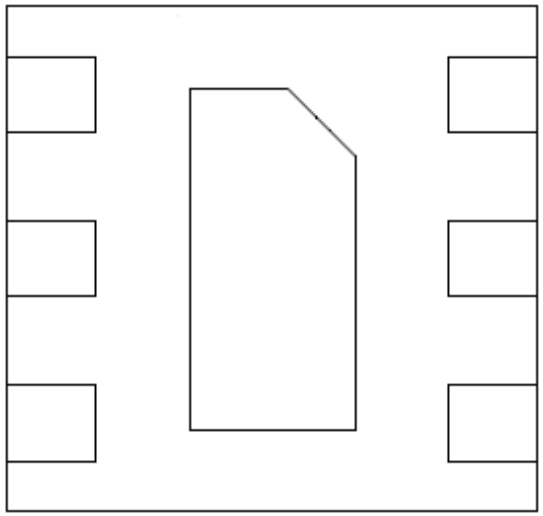
For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@RENESAS.COM	Europe: PCN-EU@RENESAS.COM	Japan: PCN-JP@RENESAS.COM	Asia Pac: PCN-APAC@RENESAS.COM

Appendix A - Qualification Plan (see attached)

Test Description	Condition	ISL29020IROZ-T7S2705 6 Lead ODFN 2.1mm x 2.0mm x 0.75mm Package
Moisture Sensitivity Classification		N=44 Acc=0 L3 Pb-Free
Early Life Failure Rate +125°C	48 hours	N=2400 Acc=0
High Temperature Operating Life (HTOL) +125°C	168, 500, 1000 hours	N=240 Acc=0
Bias High Accelerated Stress Test (b-HAST) +110°C / 85% RH	264 hours	N=240 Acc=0
Unbias High Accelerated Stress Test (uHAST) +110°C / 85% RH	264 hours	N=240 Acc=0
Hot Temperature Storage (HTS) +125°C	168, 500, 1000 hours	N=50 Acc=0
Temperature Cycling Test (TCT) -55°C / +125°C	200, 500, 1000 cycles	N=240 Acc=0

Appendix B – Minor change to the POD

Existing POD



New POD – with four (4) exposed pad (tie bar)